505000904 07/12/2018

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHIVASUBRAMANIAN BALASUBRAMANIAN	06/29/2018
DILAN SENEVIRATNE	06/29/2018

RECEIVING PARTY DATA

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City:	SANTA CLARA	
State/Country:	CALIFORNIA	
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16020271

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ATTORNEY DOCKET NUMBER:	1884.486US1	
NAME OF SUBMITTER:	NANCY CUNDALL	
SIGNATURE:	/Nancy Cundall/	
DATE SIGNED:	07/12/2018	

Total Attachments: 3

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PATENT 505000904 REEL: 046333 FRAME: 0779

RECORDATION FORM COVER SHEET PATENTS ONLY

Patent and Trademark Office Attv Ref/Docket No.: (AA7059-US) 1884.486US1 To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof. 2. Name and address of receiving party(ies): 1. Name of conveying party(ies): Name: Intel Corporation Shivasubramanian Balasubramanian, Dilan Seneviratne Street Address: 2200 Mission College Blvd. Additional name(s) of conveying party(ies) attached? City: Santa Clara State: CA Zip: 95054 []Yes [X]No Country: United States of America Additional name(s) & address(es) attached? []Yes [X]No 3. Nature of conveyance: [X] Assignment [] Merger [] Security Agreement [] Change of Name [] Other Execution Date: June 29, 2018, June 29, 2018 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) B. Patent No.(s) Serial No. 16/020,271 Additional numbers attached? []Yes [X]No 6. Total number of applications and patents involved: 1 5. Name and address of party to whom correspondence concerning document should be mailed: 7. Total fee (37 CFR 3.41):\$ 0.00 Name: John N. Greaves **ПEnclosed** [Authorized to be charged to deposit account Address: 190743 Schwegman Lundberg & Woessner, P.A. P.O. Box 2938 Please charge any additional fees or credit any over Minneapolis, Minnesota 55402 payments to our Deposit Account No.: 190743 DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. 12. July 2018 John N. Greaves/Reg. No. 40,362 Name of Person Signing Signature Total number of pages including cover sheet: 3 Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks Mail Stop Assignment Recordation Services P.O. Box 1450 Alexandria, VA 22313-1450

> PATENT REEL: 046333 FRAME: 0780

Inul Docket No.: AA7059-US SLW Reference No.: (AA7059-US) 1884.486US1

<u>ASSIGNMENT</u>

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Shivasubramanian Balasubramanian, Dilan Seneviratne>

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

PACKAGE-EMBEDDED THIN-FILM CAPACITORS, PACKAGE-INTEGRAL MAGNETIC INDUCTORS, AND METHODS OF ASSEMBLING SAME

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on June 27, 2018 as

United States of America Application Number 16/020,271

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute

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all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Shiyasubramanian Balasubramanian

Dilan Seneviratne

(/29/20(8 Date Signed